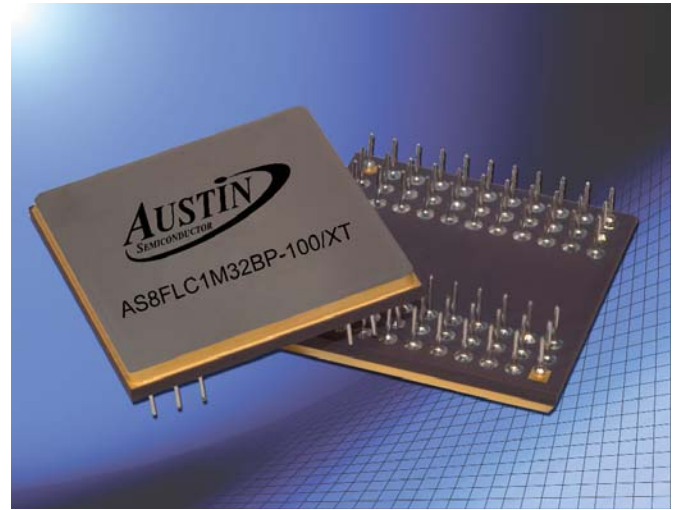




AS8FLC1M32 & AS8FLC2M32

32Mb & 64Mb 3.3V Boot Block
Flash Array



32Mb & 64Mb Hermetic Flash Multi-Chip Module FEATURES

- 32Mb device, total density, organized as 1M x 32 /
64Mb device, total density, organized as 2M x 32
- Bottom boot block (sector) architecture
- Operation with single 3.3V Supply
- Available in multiple access time variations
- Individual byte control via individual byte selects (CSx\)
- Low Power CMOS
- 100,000 Erase/Program Cycles
- Minimum 100,000 Program/Erase Cycles per sector
guaranteed
- Sector Architecture:
One 16K byte, two 8K byte, one 32K byte and
thirty-one 64Kbyte sectors (byte mode)
- Any combination of sectors can be concurrently erased
- MCM supports full array (multi-chip) Erase
- Embedded Erase and Program Algorithms
- Erase Suspend/Resume; Supports reading data from or
programming data to a sector not being Erased
- TTL Compatible Inputs and Outputs

APPLICATIONS

- Core program boot code storage
- Navigation / GPS / RADAR
- Missile control & guidance
- Automotive / industrial applications
- Weapons control & guidance

BENEFITS

- DSCC SMD 5962-09205 approved (1Mx32)
DSCC SMD 5962-08245 approved (2Mx32)
- -55C to 125C Temperature operation
- Reliable Non-Volatile High speed Memory
Access <70ns
- Very Low operating(120mA max) &
Std-by Power(150uA max)
- 100,000 Write/Erase Cycles min
- 66PGA or 68CQFP low profile Ceramic
package
- Boot Block Sector Architecture

OPTIONS

Ceramic Package

- Quad Flat Pack 68 QFP
- Hex Inline Pack 66 PGA

Timing (Cycle Time)

- 70ns - 120ns

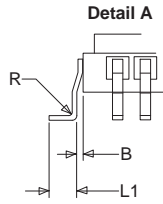
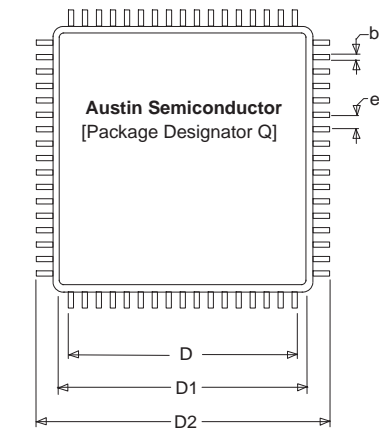
Operating Temperature Ranges

- Full Military Temp (MIL-PRF-38534, Class H)
- Military Temp (-55°C to +125° C)
- Industrial Temp (-40°C to +85° C)

*For more information or to view a complete
datasheet, please visit our website at
www.austinsemiconductor.com
or call (512) 339-1188.*

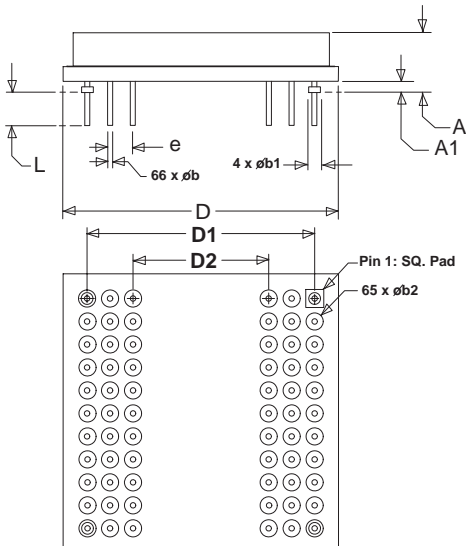
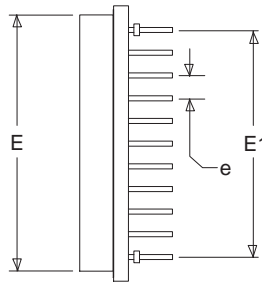
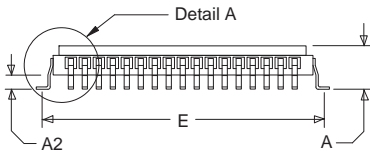
www.austinsemiconductor.com

MECHANICAL DEFINITIONS



Austin Semi Package Specifications		
Symbol	Min	Max
A	0.120	0.140
A2	0.005	0.015
B	0.010 REF	
b	0.013	0.017
D	0.800 BSC	
D1	0.870	0.890
D2	0.980	1.000
E	0.936	0.956
e	0.050 BSC	
R	0.010 TYP	
L1	0.035	0.045

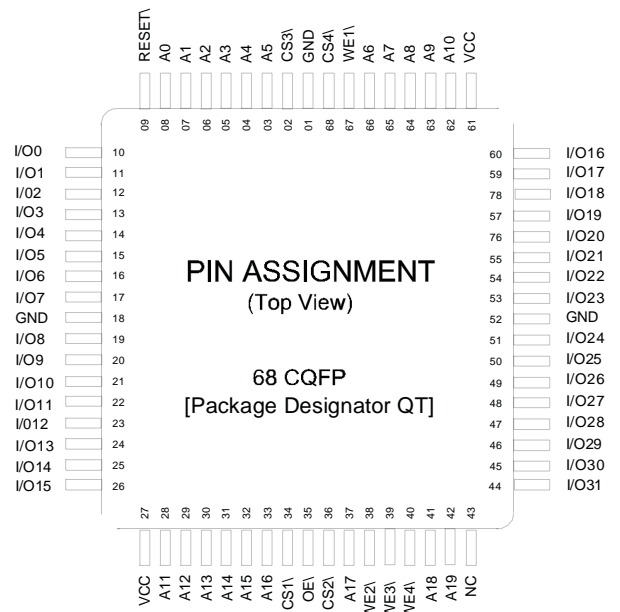
Dimensions in Inches



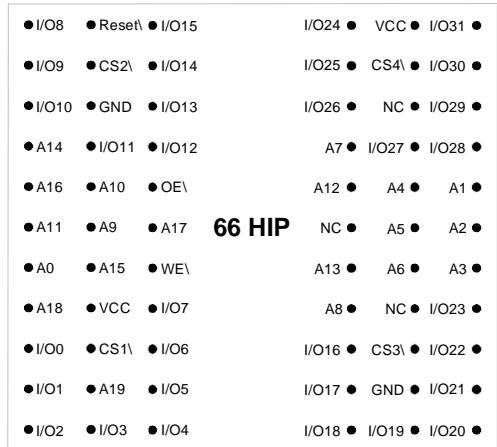
Austin Semi Package Specifications		
Symbol	Min	Max
A	0.210	0.245
A1	0.025	0.035
A2	0.135	0.145
øb	0.016	0.020
øb1	0.045	0.055
øb2	0.065	0.075
D/E	1.170	1.200
D1/E1	1.000 BSC	
D2	0.600 BSC	
D3	1.140	1.150
e	0.100 BSC	
L	0.145	0.155

Dimensions in Inches

PIN ASSIGNMENT



Pin Assignment (Top View)



8701 Cross Park Drive
Austin, Texas 78754

Phone: 512.339.1188
Fax: 512.835.8358

info@austinsemiconductor.com
www.austinsemiconductor.com



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